

ABSTRACT OF THE DISCLOSURE

Provided is an envelope which includes: a first substrate; a second substrate opposed to the first substrate; a frame interposed between the first substrate and the second substrate; and a low melting point metal for bonding the first substrate and the frame to each other. In particular, in such a configuration, the substrate or the frame has a first region and a second region which are brought into contact with the low melting point metal, and in the first region, a material capable of higher maintaining airtightness with the low melting point metal than the second region is in contact with the low melting point metal, while in the second region, a material having a stronger binding power on the low melting point metal than the first region is in contact with the low melting point metal.